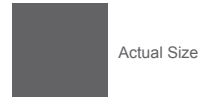
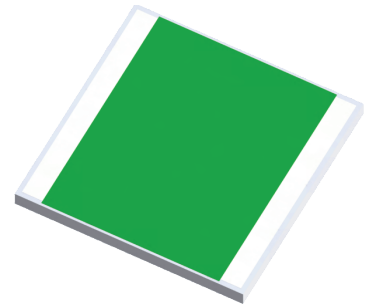


**RM5050ZZ-XXXXWN-99 Features:**

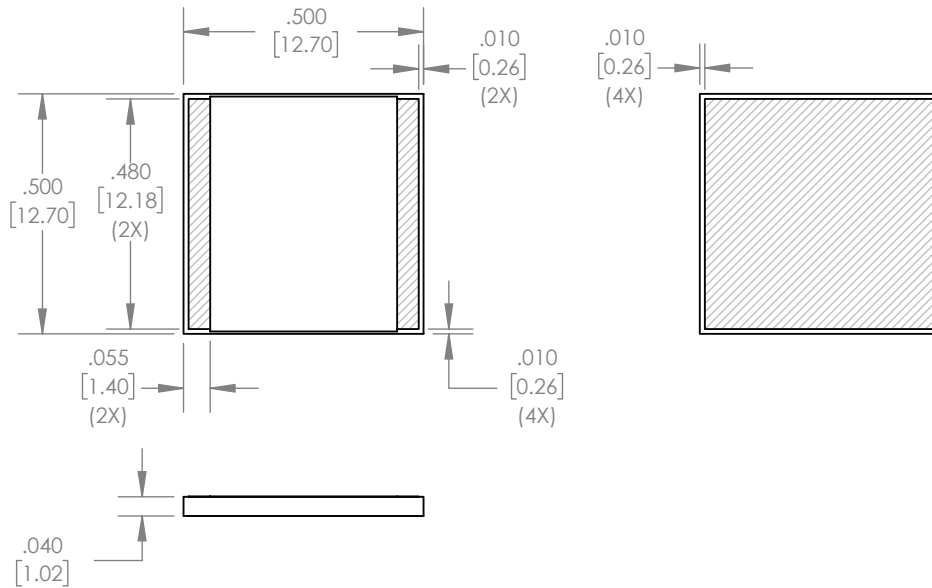
- Single-Sided Terminals w/ Backplane Configuration
- Solder, Epoxy or Wirebondable Terminals
- Solder or Epoxy Mount Backplane
- Customer Defined Testing Available
- RoHS Compliant or SnPb Available
- Non-Magnetic Available

**RM5050ZZ-XXXXWN-99 Parameters:**

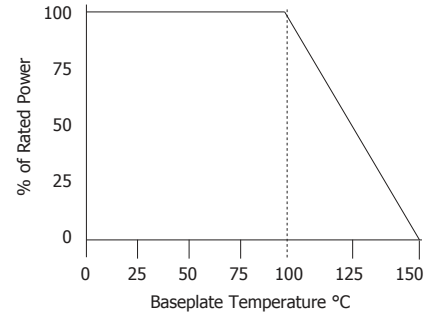
Resistance Range: 0.5Ω - 1MΩ  
 Rated Power:\* 400W  
 Construction: Thick Film on 0.040" BeO  
 Operating Temperature: -55 to +150°C  
 \* Rating based on ≤100°C constant baseplate temperature



**RM5050ZZ-XXXXWN-99 Dimensions:**



**RM5050ZZ-XXXXWN-99  
Power Derating Curve**



Dimensions in inches [mm]  
 Tolerance is ± 0.005 [0.13]  
 unless otherwise stated

**Ordering Information:**

**Example Part Number: RM5050CB-50R0JN-99**

RM	5050	ZZ	-	XXXX	W	N	-	99
Prefix for Resistor w/ Single-Sided Terminals and Backplane				Value Code 50R0 - 50Ω 1000 - 100Ω 1001 - 1KΩ 1004 - 1MΩ	Tolerance F - 1% G - 2% J - 5%	Normal Inspection Contact factory for additional options		Substrate 99 - 0.040" BeO
Size 5050								

Terminal Metallization	RoHS	Magnetic	Solder	Epoxy	Wirebond
AS - Tin Lead over Platinum Palladium Gold	No	No	Yes	No	No
CB - Tin Lead over Nickel over Silver	No	Yes	Yes	No	No
CC - 100% Matte Tin over Copper over Silver	Yes	No	Yes	No	No
CT - 100% Matte Tin over Nickel over Silver	Yes	Yes	Yes	No	No
HA - Gold over Platinum Gold I/O Terminals w/ Platinum Palladium Gold Backplane	Yes	No	Yes (Backplane)	Yes	Yes (I/O Terminals)
JA - Gold over Platinum Palladium Gold	Yes	No	No	Yes	Yes

Barry Industries reserves the right to change part number and/or process without notification.

**RM5050ZZ-XXXXWN-99 Reliability Specifications:**

Parameter:	Test Condition:	Results:
Short Time Overload	Apply 1.1x Rated Power for 5 Seconds.	≤ 5.0% Resistance Shift
Rated Load Life	Apply 1/2 Power Under 40°C ±2°C 90 Minutes on/ 30 Minutes off. Repeat for 100 hours	≤ 5.0% Resistance Shift
Moisture Resistance	MIL-PRF-55342 Para 4.8.9 95% RH, 25°C - 65°C	≤ 5.0% Resistance Shift
Resistance to Soldering Heat	MIL-STD-202-210 and MIL-PRF-55342 Para 4.8.8.1	≤ 5.0% Resistance Shift
Resistance to Bonding Exposure	MIL-PRF-55342 Para 4.8.8.2	≤ 5.0% Resistance Shift
Solderability	MIL-PRF-55342 Para 4.8.12	>95% Covered
High Temperature Storage	125°C ±2°C for 500 Hours	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)
Thermal Shock	-65 to +150 30 Minutes Dwell, 5 Cycles	1.) ≤ 5.0% Resistance Shift 2.) No Significant Abnormality (Visual)

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